



PK738 (v1.0) May 29, 2015

# 100% Material Declaration Data Sheet Spartan®-6 Cu Wire FGG900 Package

**Average Weight: 4.11 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.090946</b>	<b>2.213%</b>
	Silicon	7440-21-3	100.00	Main material	0.090946	
<b>Die Attach Material</b>					<b>0.016016</b>	<b>0.390%</b>
	Silver	7440-22-4	77.50	Main material	0.012412	
	Bismaleimide monomer	Trade Secret	15.00	Main material	0.002402	
	Acrylate monomer	Trade Secret	7.50	Main material	0.001201	
<b>Copper Wire</b>					<b>0.008441</b>	<b>0.205%</b>
	Cu	7440-50-8	98.25	Main material	0.008293	
	Pd	7440-05-3	1.75	Dopant	0.000148	
<b>Mold Compound</b>					<b>1.878392</b>	<b>45.703%</b>
	Epoxy Resin	Trade secret	3.00	Main material	0.056352	
	Phenol Resin A	9003-35-4	3.00	Main material	0.056352	
	Phenol Resin B	Trade secret	3.00	Main material	0.056352	
	Silica(Amorphous) A	60676-86-0	72.45	Filler	1.360895	
	Silica(Amorphous) B	7631-86-9	15.00	Filler	0.281759	
	Metal Hydroxide	Trade secret	3.00	Flame retardant	0.056352	
	Carbon black	1333-86-4	0.55	Color agent	0.010331	
<b>Solder Balls</b>					<b>0.751829</b>	<b>18.293%</b>
	Tin (Sn)	7440-31-5	96.50	Main material	0.725515	
	Silver (Ag)	7440-22-4	3.00	Main material	0.022555	
	Copper (Cu)	7440-50-8	0.50	Main material	0.003759	

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Substrate					<b>1.364376</b>	<b>33.197%</b>
	Au	7440-57-5	1.18	Main material	0.016077	
	Ni	7440-02-0	8.36	Main material	0.114059	
	Cu foil	7440-50-8	2.56	Main material	0.034922	
	Cu plating	7440-50-8	18.45	Plating	0.251726	
	Continuous Filament Fiber Glass	65997-17-3	19.06	Glass Fiber	0.260040	
	BT Core	7440-50-8 N/A	34.76	Core	0.474263	
	Solder Mask	14807-96-6 7727-43-7 7631-86-9 34590-94-8 91-20-3 85954-11-6 N/A	11.21	Solder mask	0.152928	
	Prepregs	NA	4.42	Prepregs	0.060362	

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
5/29/15	1.0	Initial Xilinx release

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